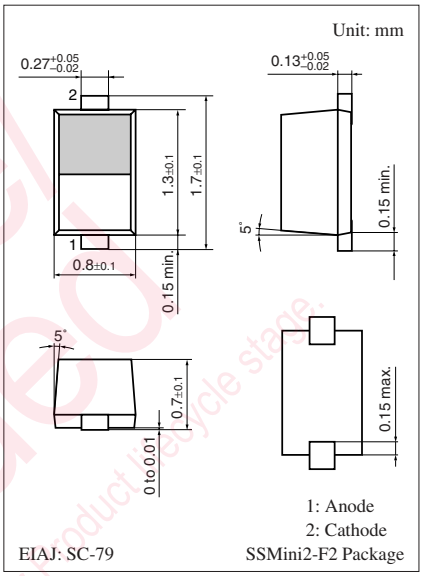
MA2S077

Silicon epitaxial planar type

For band switching



Marking Symbol: S

■ Features

- Low forward dynamic resistance r_f
- Less voltage dependence of diode capacitance C_D
- SS-Mini type package, allowing downsizing of equipment and automatic insertion through the taping package

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	35	V
Forward current	I_F	100	mA
Operating ambient temperature *	T_{opr}	−25 to +85	°C
Storage temperature	T_{stg}	−55 to +150	°C

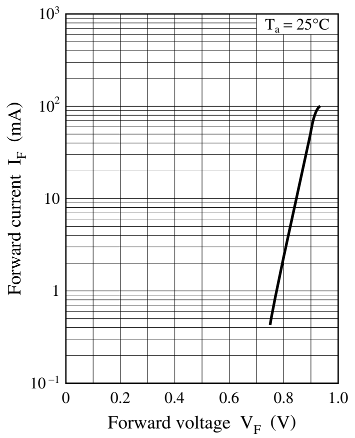
Note) ∗: Maximum ambient temperature during operation.

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

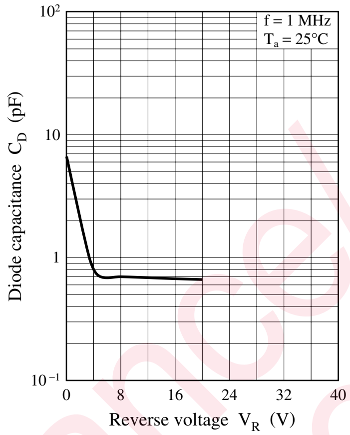
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA		0.92	1.00	V
Reverse current	I_R	$V_R = 33$ V		0.01	100.00	nA
Diode capacitance	C_D	$V_R = 6$ V, f = 1 MHz		0.9	1.2	pF
Forward dynamic resistance *	r_f	$I_F = 2$ mA, f = 100 MHz		0.65	0.85	Ω

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. ∗: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

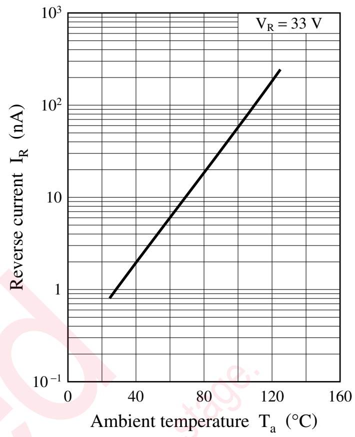
I_F — V_F



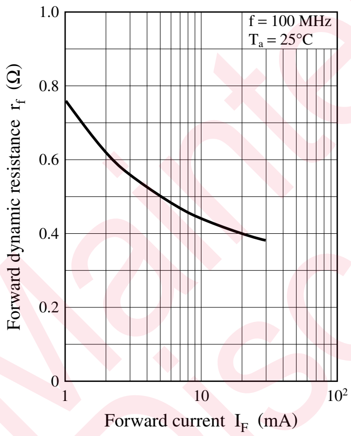
C_D — V_R



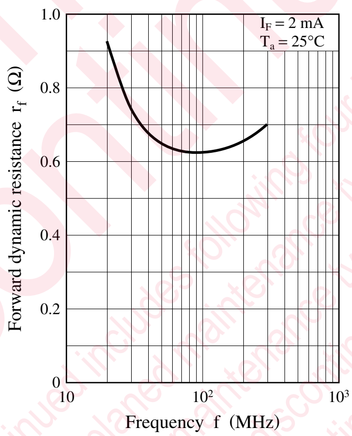
I_R — T_a



r_f — I_F



r_f — f



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